

C2220C103F2TACTU

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Aliases (C2220C103F2TAC7800) SMD Comm X8G HT150C, Ceramic, 0.01 uF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	130 mg
Shelf Life	78 Weeks
MSL	1

mensions		Spec
nip Size	2220	Capa
	5.7mm +/-0.4mm	Meas
	5mm +/-0.4mm	Toler
	1mm +/-0.15mm	Volta
	3.5mm MIN	Diele
	0.6mm +/-0.35mm	Tem
		Tom

Packaging Specifications Packaging

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	Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity 1000	Packaging Quantity	1000

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1%1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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